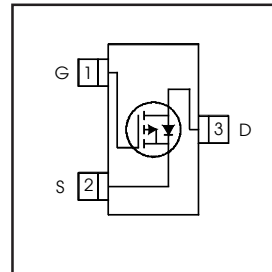


- Ultra Low On-Resistance
- P-Channel MOSFET
- SOT-23 Footprint
- Low Profile (<1.1mm)
- Available in Tape and Reel
- Fast Switching
- 1.8V Gate Rated
- Lead-Free
- RoHS Compliant, Halogen-Free

### HEXFET® Power MOSFET



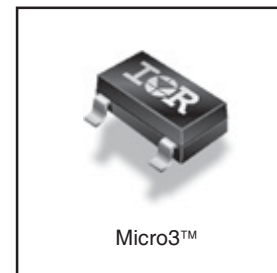
$$V_{DS} = -12V$$

$$R_{DS(on)} = 0.05\Omega$$

### Description

These P-Channel MOSFETs from International Rectifier utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET® power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in battery and load management.

A thermally enhanced large pad leadframe has been incorporated into the standard SOT-23 package to produce a HEXFET Power MOSFET with the industry's smallest footprint. This package, dubbed the Micro3™, is ideal for applications where printed circuit board space is at a premium. The low profile (<1.1mm) of the Micro3 allows it to fit easily into extremely thin application environments such as portable electronics and PCMCIA cards. The thermal resistance and power dissipation are the best available.



| Base Part Number | Package Type     | Standard Pack |          | Orderable Part Number |
|------------------|------------------|---------------|----------|-----------------------|
|                  |                  | Form          | Quantity |                       |
| IRLML6401TRPbF   | Micro3™ (SOT-23) | Tape and Reel | 3000     | IRLML6401TRPbF        |

### Absolute Maximum Ratings

|                          | Parameter                                  | Max.         | Units |
|--------------------------|--------------------------------------------|--------------|-------|
| $V_{DS}$                 | Drain- Source Voltage                      | -12          | V     |
| $I_D @ T_A = 25^\circ C$ | Continuous Drain Current, $V_{GS} @ -4.5V$ | -4.3         | A     |
| $I_D @ T_A = 70^\circ C$ | Continuous Drain Current, $V_{GS} @ -4.5V$ | -3.4         |       |
| $I_{DM}$                 | Pulsed Drain Current ①                     | -34          |       |
| $P_D @ T_A = 25^\circ C$ | Power Dissipation                          | 1.3          | W     |
| $P_D @ T_A = 70^\circ C$ | Power Dissipation                          | 0.8          |       |
|                          | Linear Derating Factor                     | 0.01         | W/°C  |
| $E_{AS}$                 | Single Pulse Avalanche Energy④             | 33           | mJ    |
| $V_{GS}$                 | Gate-to-Source Voltage                     | $\pm 8.0$    | V     |
| $T_J, T_{STG}$           | Junction and Storage Temperature Range     | -55 to + 150 | °C    |

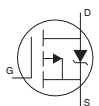
### Thermal Resistance

|                 | Parameter                    | Typ. | Max. | Units |
|-----------------|------------------------------|------|------|-------|
| $R_{\theta JA}$ | Maximum Junction-to-Ambient③ | 75   | 100  | °C/W  |

**Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

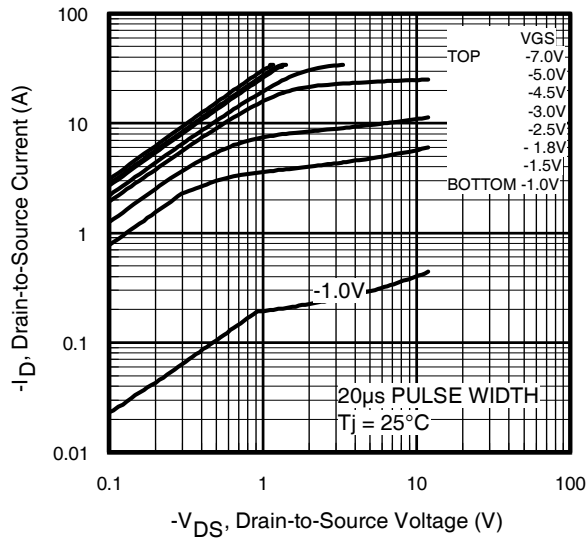
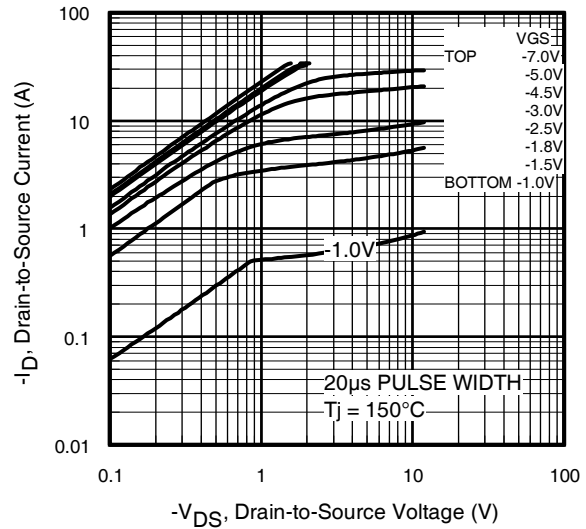
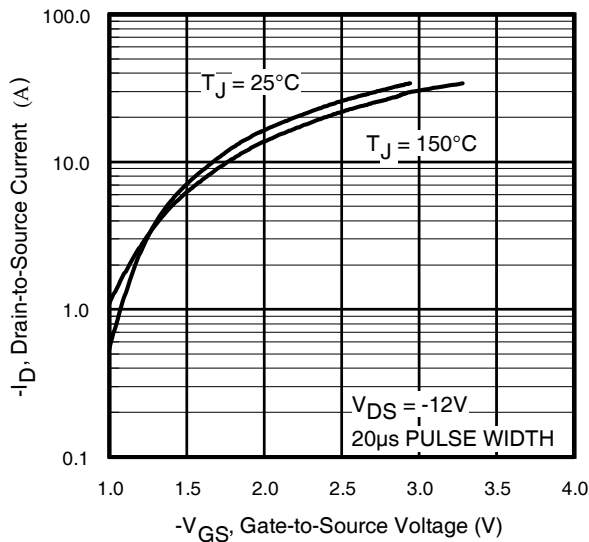
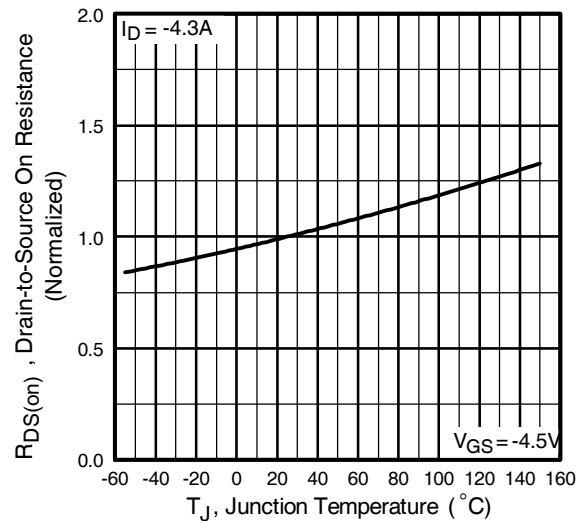
|                                 | Parameter                            | Min.  | Typ.   | Max.  | Units               | Conditions                                                  |
|---------------------------------|--------------------------------------|-------|--------|-------|---------------------|-------------------------------------------------------------|
| $V_{(BR)DSS}$                   | Drain-to-Source Breakdown Voltage    | -12   | —      | —     | V                   | $V_{GS} = 0V$ , $I_D = -250\mu A$                           |
| $\Delta V_{(BR)DSS}/\Delta T_J$ | Breakdown Voltage Temp. Coefficient  | —     | -0.007 | —     | V/ $^\circ\text{C}$ | Reference to $25^\circ\text{C}$ , $I_D = -1\text{mA}$       |
| $R_{DS(on)}$                    | Static Drain-to-Source On-Resistance | —     | —      | 0.050 | $\Omega$            | $V_{GS} = -4.5V$ , $I_D = -4.3A$ ②                          |
|                                 |                                      | —     | —      | 0.085 |                     | $V_{GS} = -2.5V$ , $I_D = -2.5A$ ②                          |
|                                 |                                      | —     | —      | 0.125 |                     | $V_{GS} = -1.8V$ , $I_D = -2.0A$ ②                          |
| $V_{GS(th)}$                    | Gate Threshold Voltage               | -0.40 | -0.55  | -0.95 | V                   | $V_{DS} = V_{GS}$ , $I_D = -250\mu A$                       |
| $g_{fs}$                        | Forward Transconductance             | 8.6   | —      | —     | S                   | $V_{DS} = -10V$ , $I_D = -4.3A$                             |
| $I_{DSS}$                       | Drain-to-Source Leakage Current      | —     | —      | -1.0  | $\mu A$             | $V_{DS} = -12V$ , $V_{GS} = 0V$                             |
|                                 |                                      | —     | —      | -25   |                     | $V_{DS} = -9.6V$ , $V_{GS} = 0V$ , $T_J = 55^\circ\text{C}$ |
| $I_{GSS}$                       | Gate-to-Source Forward Leakage       | —     | —      | -100  | nA                  | $V_{GS} = -8.0V$                                            |
|                                 | Gate-to-Source Reverse Leakage       | —     | —      | 100   |                     | $V_{GS} = 8.0V$                                             |
| $Q_g$                           | Total Gate Charge                    | —     | 10     | 15    | nC                  | $I_D = -4.3A$                                               |
| $Q_{gs}$                        | Gate-to-Source Charge                | —     | 1.4    | 2.1   |                     | $V_{DS} = -10V$                                             |
| $Q_{gd}$                        | Gate-to-Drain ("Miller") Charge      | —     | 2.6    | 3.9   |                     | $V_{GS} = -5.0V$ ②                                          |
| $t_{d(on)}$                     | Turn-On Delay Time                   | —     | 11     | —     | ns                  | $V_{DD} = -6.0V$                                            |
| $t_r$                           | Rise Time                            | —     | 32     | —     |                     | $I_D = -1.0A$                                               |
| $t_{d(off)}$                    | Turn-Off Delay Time                  | —     | 250    | —     |                     | $R_D = 6.0\Omega$                                           |
| $t_f$                           | Fall Time                            | —     | 210    | —     |                     | $R_G = 89\Omega$ ②                                          |
| $C_{iss}$                       | Input Capacitance                    | —     | 830    | —     | pF                  | $V_{GS} = 0V$                                               |
| $C_{oss}$                       | Output Capacitance                   | —     | 180    | —     |                     | $V_{DS} = -10V$                                             |
| $C_{rss}$                       | Reverse Transfer Capacitance         | —     | 125    | —     |                     | $f = 1.0\text{MHz}$                                         |

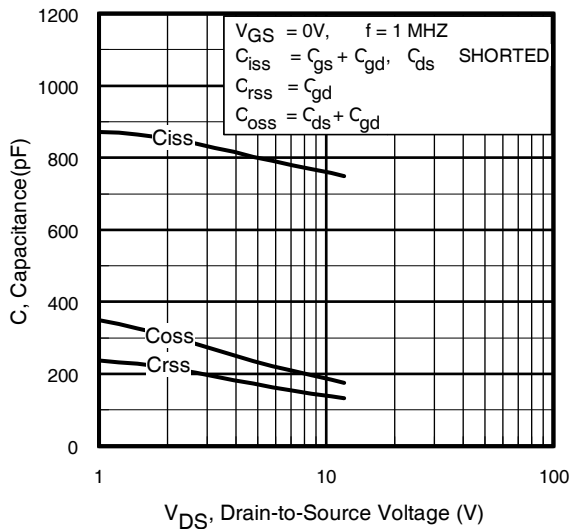
**Source-Drain Ratings and Characteristics**

|          | Parameter                              | Min. | Typ. | Max. | Units | Conditions                                                                                                                                           |
|----------|----------------------------------------|------|------|------|-------|------------------------------------------------------------------------------------------------------------------------------------------------------|
| $I_S$    | Continuous Source Current (Body Diode) | —    | —    | -1.3 | A     | MOSFET symbol showing the integral reverse p-n junction diode.  |
| $I_{SM}$ | Pulsed Source Current (Body Diode) ①   | —    | —    | -34  |       |                                                                                                                                                      |
| $V_{SD}$ | Diode Forward Voltage                  | —    | —    | -1.2 | V     | $T_J = 25^\circ\text{C}$ , $I_S = -1.3A$ , $V_{GS} = 0V$ ②                                                                                           |
| $t_{rr}$ | Reverse Recovery Time                  | —    | 22   | 33   | ns    | $T_J = 25^\circ\text{C}$ , $I_F = -1.3A$                                                                                                             |
| $Q_{rr}$ | Reverse Recovery Charge                | —    | 8.0  | 12   | nC    | $di/dt = -100A/\mu s$ ②                                                                                                                              |

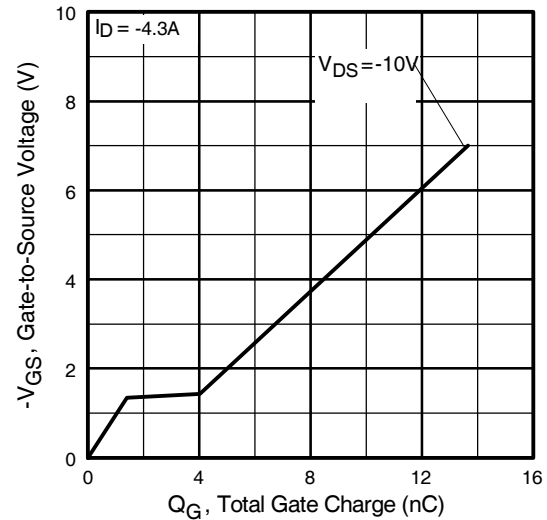
**Notes:**

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width  $\leq 300\mu s$ ; duty cycle  $\leq 2\%$ .
- ③ Surface mounted on 1" square single layer 1oz. copper FR4 board, steady state.
- ④ Starting  $T_J = 25^\circ\text{C}$ ,  $L = 3.5\text{mH}$   
 $R_G = 25\Omega$ ,  $I_{AS} = -4.3A$ .

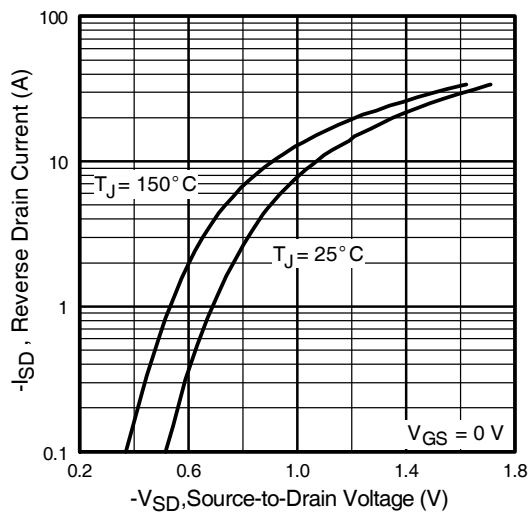

**Fig 1.** Typical Output Characteristics

**Fig 2.** Typical Output Characteristics

**Fig 3.** Typical Transfer Characteristics

**Fig 4.** Normalized On-Resistance Vs. Temperature



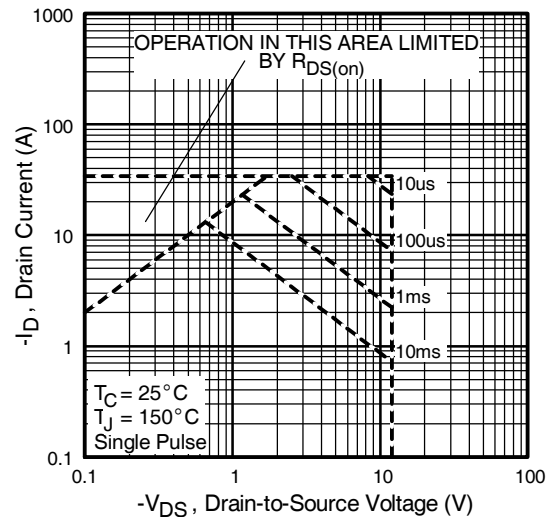
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



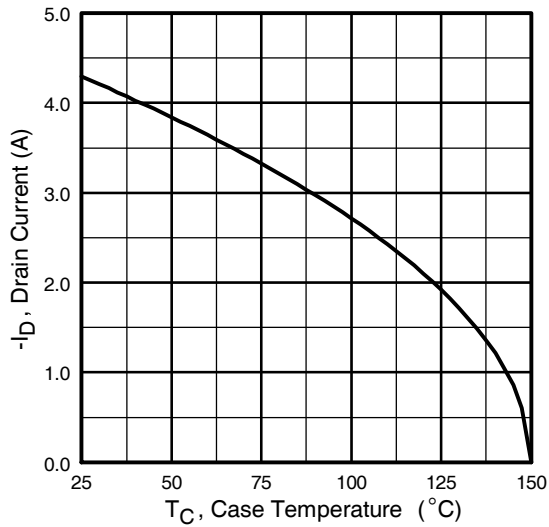
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



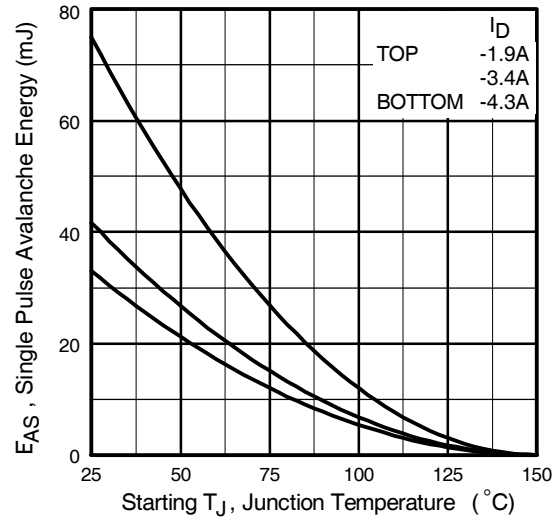
**Fig 7.** Typical Source-Drain Diode Forward Voltage



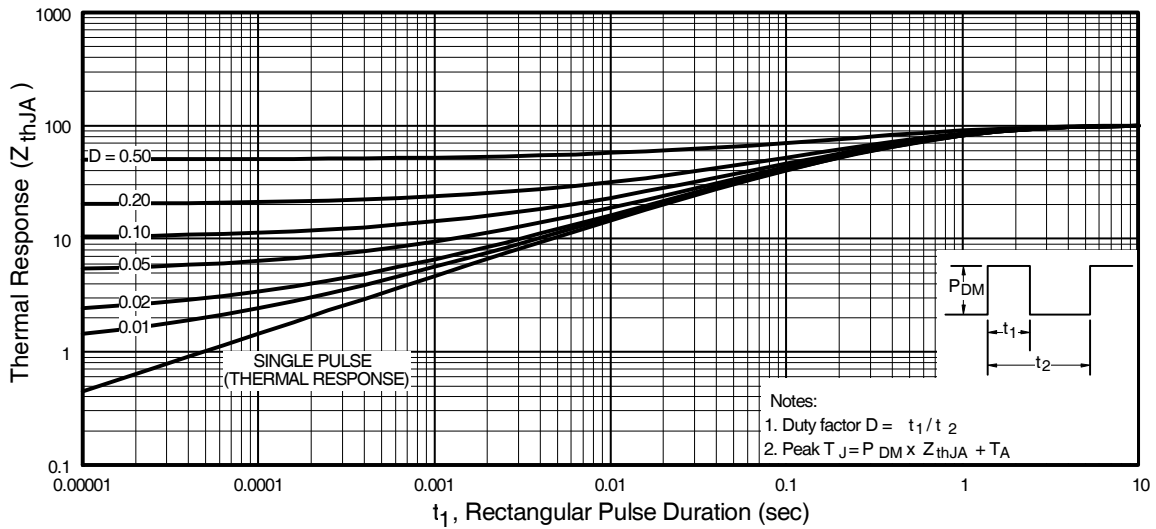
**Fig 8.** Maximum Safe Operating Area



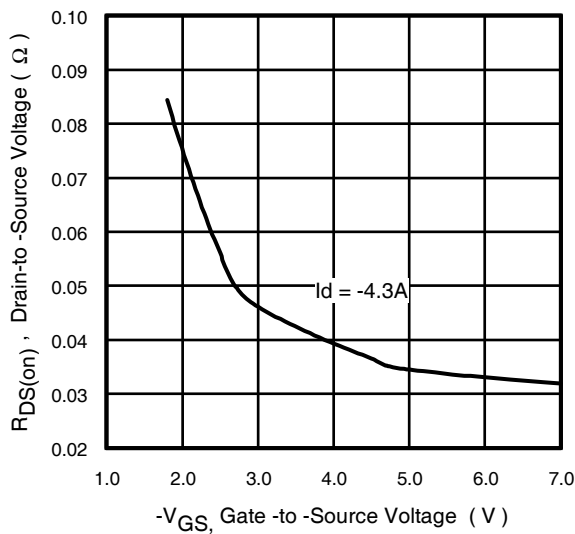
**Fig 9.** Maximum Drain Current Vs. Case Temperature



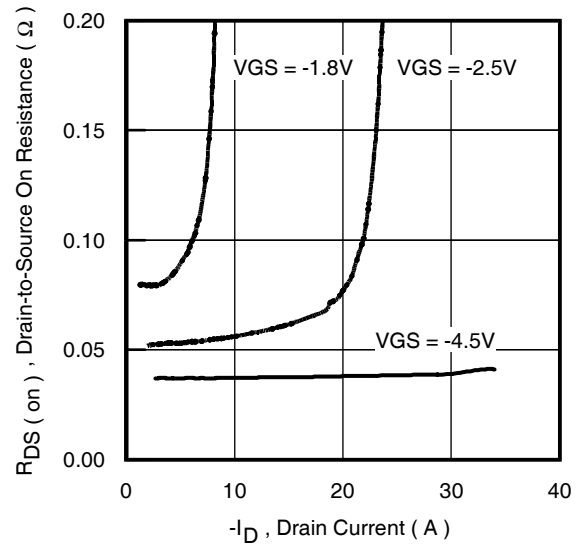
**Fig 10.** Maximum Avalanche Energy Vs. Drain Current



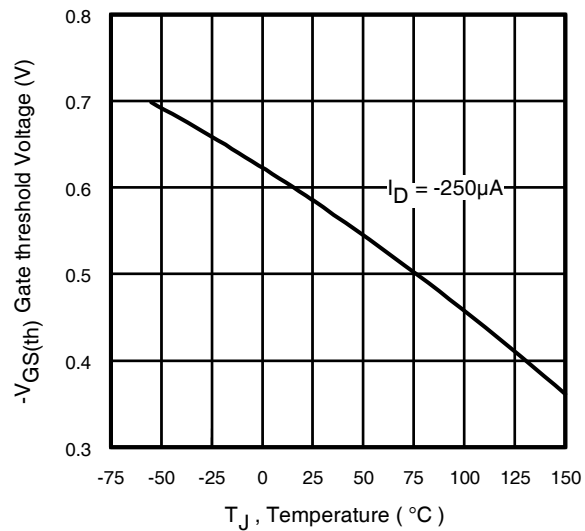
**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



**Fig 12.** Typical On-Resistance Vs. Gate Voltage



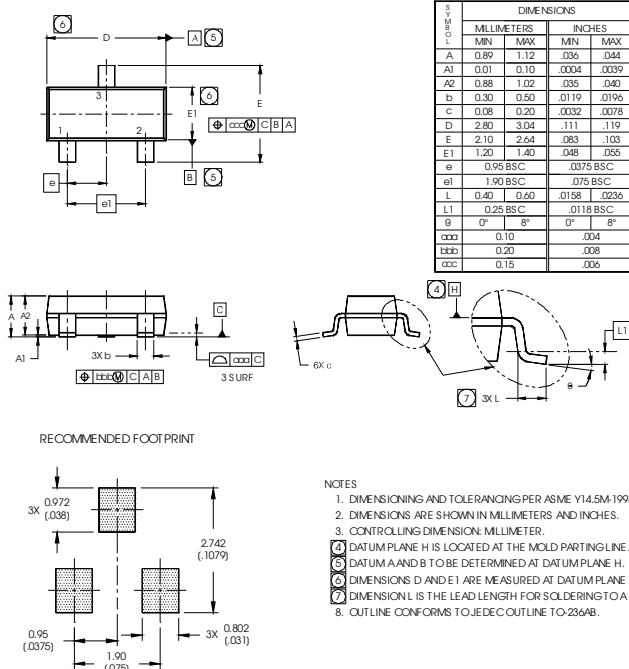
**Fig 13.** Typical On-Resistance Vs. Drain Current



**Fig 14.** Typical Threshold Voltage Vs. Junction Temperature

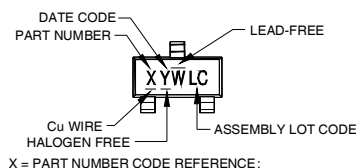
## Micro3 (SOT-23) (Lead-Free) Package Outline

Dimensions are shown in millimeters (inches)



## Micro3 (SOT-23 / TO-236AB) Part Marking Information

Notes: This part marking information applies to devices produced after 02/26/2001



X = PART NUMBER CODE REFERENCE:

|               |               |
|---------------|---------------|
| A = IRLML2402 | S = IRLML6244 |
| B = IRLML2803 | T = IRLML6246 |
| C = IRLML6302 | U = IRLML6344 |
| D = IRLML5103 | V = IRLML6346 |
| E = IRLML6402 | W = IRFML8244 |
| F = IRLML6401 | X = IRLML2244 |
| G = IRLML2502 | Y = IRLML2246 |
| H = IRLML5203 | Z = IRFML9244 |
| I = IRLML0030 |               |
| J = IRLML2030 |               |
| K = IRLML0100 |               |
| L = IRLML0060 |               |
| M = IRLML0040 |               |
| N = IRLML2060 |               |
| P = IRLML9301 |               |
| R = IRLML9303 |               |

DATE CODE EXAMPLE:  
YWW = 432 = DF  
YWW = 503 = 5C

W = (1-26) IF PRECEDED BY LAST DIGIT OF CALENDAR YEAR

| YEAR | Y    | WORK WEEK | W    |
|------|------|-----------|------|
| 2011 | 2001 | 01        | A    |
| 2012 | 2002 | 02        | B    |
| 2013 | 2003 | 03        | C    |
| 2014 | 2004 | 04        | D    |
| 2015 | 2005 | 5         |      |
| 2016 | 2006 | 6         |      |
| 2017 | 2007 | 7         |      |
| 2018 | 2008 | 8         |      |
| 2019 | 2009 | 9         |      |
| 2020 | 2010 | 0         | 24 X |
|      |      |           | 25 Y |
|      |      |           | 26 Z |

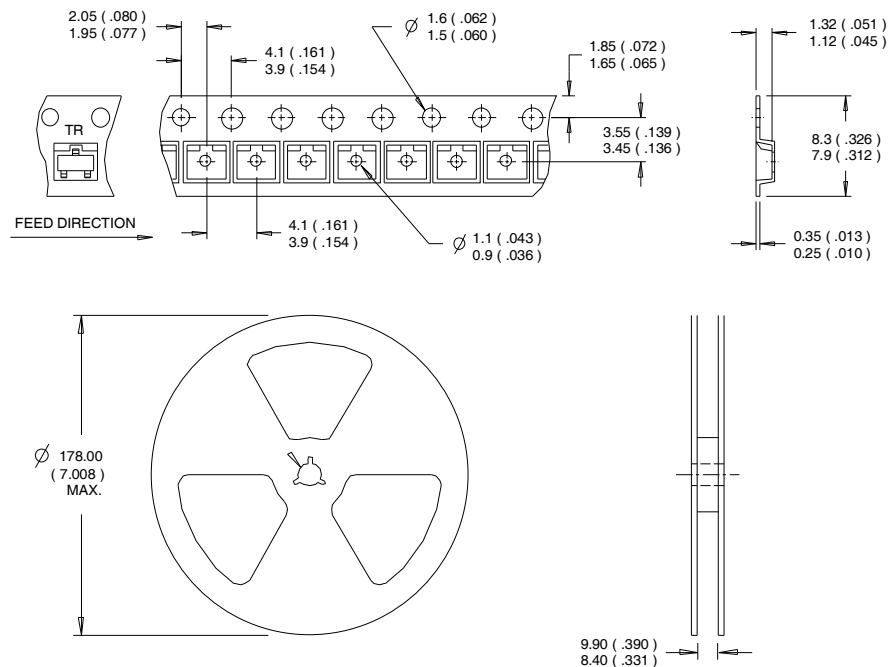
W = (27-52) IF PRECEDED BY A LETTER

| YEAR | Y    | WORK WEEK | W |
|------|------|-----------|---|
| 2011 | 2001 | A 27      | A |
| 2012 | 2002 | B 28      | B |
| 2013 | 2003 | C 29      | C |
| 2014 | 2004 | D 30      | D |
| 2015 | 2005 | E         |   |
| 2016 | 2006 | F         |   |
| 2017 | 2007 | G         |   |
| 2018 | 2008 | H         |   |
| 2019 | 2009 | J         |   |
| 2020 | 2010 | K         |   |
|      |      | 50        | X |
|      |      | 51        | Y |
|      |      | 52        | Z |

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package>

## Micro3™ Tape & Reel Information

Dimensions are shown in millimeters (inches)



NOTES:  
1. CONTROLLING DIMENSION : MILLIMETER.  
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package>



**Qualification information<sup>†</sup>**

|                            |                                                          |                                               |
|----------------------------|----------------------------------------------------------|-----------------------------------------------|
| Qualification level        | Consumer<br>(per JEDEC JESD47F <sup>††</sup> guidelines) |                                               |
| Moisture Sensitivity Level | Micro3™ (SOT-23)                                         | MSL1<br>(per JEDEC J-STD-020D <sup>††</sup> ) |
| RoHS compliant             | Yes                                                      |                                               |

<sup>†</sup> Qualification standards can be found at International Rectifier's web site: <http://www.irf.com/product-info/reliability>

<sup>††</sup> Applicable version of JEDEC standard at the time of product release

**Revision History**

| Date      | Comment                                                                                                                                                                                                                                                                                                                                 |
|-----------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 4/28/2014 | <ul style="list-style-type: none"> <li>• Updated data sheet with new IR corporate template.</li> <li>• Updated package outline &amp; part marking on page 7.</li> <li>• Added Qualification table -Qual level "Consumer" on page 9.</li> <li>• Added bullet point in the Benefits "RoHS Compliant, Halogen -Free" on page 1.</li> </ul> |

International  
 Rectifier

**IR WORLD HEADQUARTERS:** 101 N. Sepulveda Blvd., El Segundo, California 90245, USA  
 To contact International Rectifier, please visit <http://www.irf.com/whoto-call/>

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